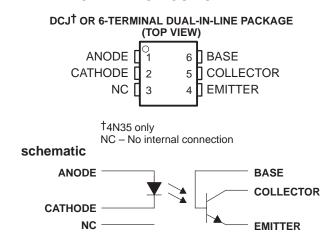
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium-Arsenide-Diode Infrared Source Optically Coupled to a Silicon npn Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation
 1.5-kV, 2.5-kV, or 3.55-kV Rating
- High-Speed Switching
 t_r = 7 μs, t_f = 7 μs Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays and Pulse Transformers
- Safety Regulatory Approval UL/CUL, File No. E65085



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Input-to-output peak voltage (8-ms half sine wave): 4N35
4N37
Collector-base voltage
Collector-emitter voltage (see Note 1)
Emitter-base voltage 7 V
Input-diode reverse voltage 6 V
Input-diode forward current: Continuous
Phototransistor continuous collector current
Continuous total power dissipation at (or below) 25°C free-air temperature:
Infrared-emitting diode (see Note 2)
Phototransistor (see Note 3)
Continuous power dissipation at (or below) 25°C lead temperature:
Infrared-emitting diode (see Note 4)
Phototransistor (see Note 5)
Operating temperature range, T _A 55°C to 100°C
Storage temperature range, T _{stg}
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. This value applies when the base-emitter diode is open-circulated.

- 2. Derate linearly to 100°C free-air temperature at the rate of 1.33 mW/°C.
- 3. Derate linearly to 100°C free-air temperature at the rate of 4 mW/°C.
- 4. Derate linearly to 100°C lead temperature at the rate of 1.33 mW/°C. Lead temperature is measured on the collector lead 0.8 mm (1/32 inch) from the case.
- 5. Derate linearly to 100°C lead temperature at the rate of 6.7 mW/°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDIT	MIN	TYP	MAX	UNIT		
V(BR)CBO	Collector-base breakdown voltage	$I_C = 100 \mu\text{A}, I_E = 0,$	IF = 0	70†			V	
V(BR)CEO	Collector-emitter breakdown voltage	$I_C = 10 \text{ mA}, I_B = 0,$	IF = 0	30†			V	
V(BR)EBO	Emitter-base breakdown voltage	$I_E = 100 \mu A, I_C = 0,$	IF = 0	7†			V	
I _R	Input diode static reverse current	V _R = 6 V				10†	μΑ	
I _{IO}	Input-to-output current	V _{IO} = rated peak value,	t = 8 ms			100	mA	
^I C(on)	On-state collector current	$V_{CE} = 10 \text{ V}, I_F = 10 \text{ m/s}$	$l_B = 0$	10†			mA	
		$V_{CE} = 10 \text{ V}, I_{F} = 10 \text{ m/s}$ $T_{A} = -55^{\circ}\text{C}$	A , $I_B = 0$,	4†				
		V _{CE} = 10 V, I _F = 10 mA T _A = 100°C	A , $I_B = 0$,	4†				
		V _{CE} = 10 V, I _F = 0	I _B = 0		1	50	nA	
I _{C(off)}	Off-state collector current	V _{CE} = 30 V, I _F = 0, T _A = 100°C	$I_B = 0$,			500†	μА	
h _{FE}	Transistor static forward current transfer ratio	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ m/s}$	A, I _F = 0		500			
VF	Input diode static forward voltage	IF = 10 mA		0.8†		1.5†	V	
		$I_F = 10 \text{ mA}, T_A = -55^\circ$	С	0.9†		1.7†		
		$I_F = 10 \text{ mA}, T_A = 100^\circ$	С	0.7†		1.4†		
VCE(sat)	Collector-emitter saturation voltage	$I_C = 0.5 \text{ mA}, I_F = 10 \text{ m/s}$	$A_{,}$ I _B = 0 mA			0.3†	V	
r _{IO}	Input-to-output internal resistance	V _{IO} = 500 V, See Note	6	1011†			Ω	
C _{io}	Input-to-output capacitance	$V_{IO} = 0$, $f = 1 MHz$,	See Note 6		1	2.5†	pF	

[†] JEDEC registered data

NOTE 6: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

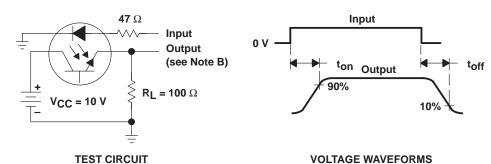
switching characteristics at 25°C free-air temperature†

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ton	Time-on time	V _{CC} = 10 V,	$I_{C(on)} = 2 \text{ mA},$		7	10	
toff	Turn-off time	$R_L = 100 \Omega$,	See Figure 1		7	10	μs

[†]JEDEC registered data



PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input waveform is supplied by a generator with the following characteristics: $Z_O = 50 \ \Omega$, $t_\Gamma \le 15 \ ns$, duty cycle $\approx 1\%$, $t_W = 100 \ \mu s$.

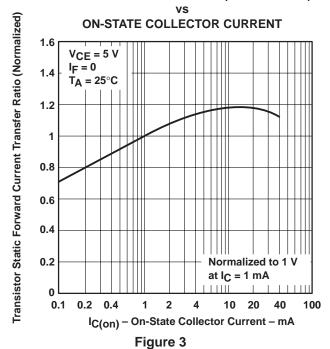
B. The output waveform is monitored on an oscilloscope with the following characteristics: $t_r \le 12$ ns, $R_{in} \ge 1$ M Ω , $C_{in} \le 20$ pF.

Figure 1. Switching Times

TYPICAL CHARACTERISTICS

OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 10,000 V_{CE} = 10 V 4,000 IC(off) - Off-State Collector Current - nA $I_B = 0$ IF = 0 1,000 400 100 40 10 1 0.4 0.1 50 T_A - Free-Air Temperature - °C Figure 2

TRANSISTOR STATIC FORWARD CURRENT TRANSFER RATIO (NORMALIZED)



IC - Collector Current - mA

0.01

TYPICAL CHARACTERISTICS

COLLECTOR CURRENT MODULATION FREQUENCY 10 $V_{CC} = 10 V$ 4 $I_B = 0$ $T_A = 25^{\circ}C$ $R_L = 100 \Omega$ 2 $R_L = 1 \Omega$ 0.4 0.2 0.1 $R_L = 475 \Omega$ 0.04 0.02

Figure 4

10

40

f_{mod} – Modulation Frequency – kHz

100

400

1000

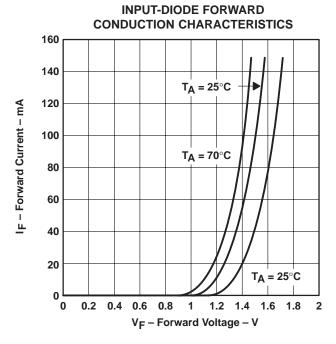


Figure 5

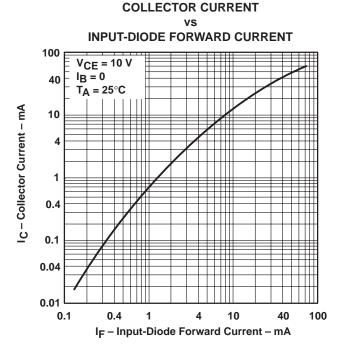
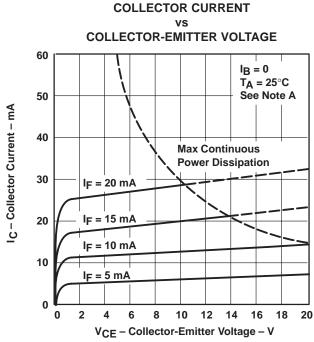


Figure 6



NOTE A. Pulse operation of input diode is required for operation beyond limits shown by dotted lines.

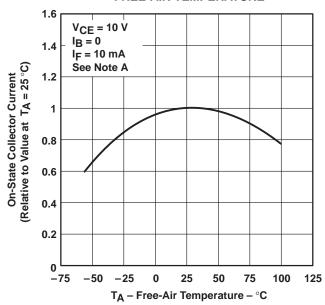
Figure 7



TYPICAL CHARACTERISTICS

ON-STATE COLLECTOR CURRENT (RELATIVE TO VALUE AT 25°C)

FREE-AIR TEMPERATURE

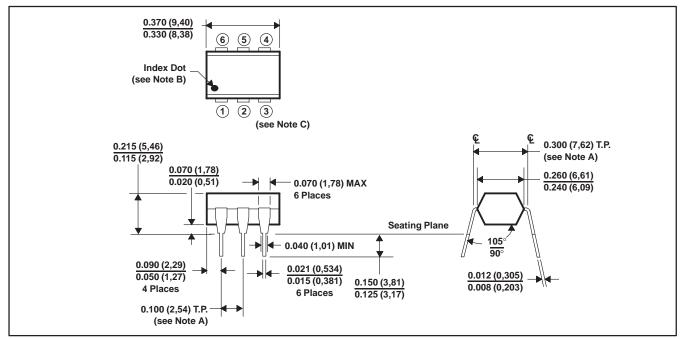


NOTE A. These parameters were measured using pulse techniques, $t_W = 1$ ms, duty cycle ≤ 2 %.

Figure 8

APPLICATION INFORMATION

The devices consist of a gallium-arsenide infrared-emitting diode and an npn silicon phototransistor. Each device is available in a 6-terminal plastic dual-in-line package, shown in Figure 9, or in a DCJ plastic dual surface-mount optocoupler package (see Mechanical Data).



- NOTES: A. Terminals are within 0.005 (0,13) radius of true position (T.P.) with maximum material condition and unit installed.
 - B. Terminal 1 identified by index dot.
 - C. The dimensions given fall within JEDEC MO-001 AM dimensions.
 - D. All linear dimensions are in inches (millimeters).

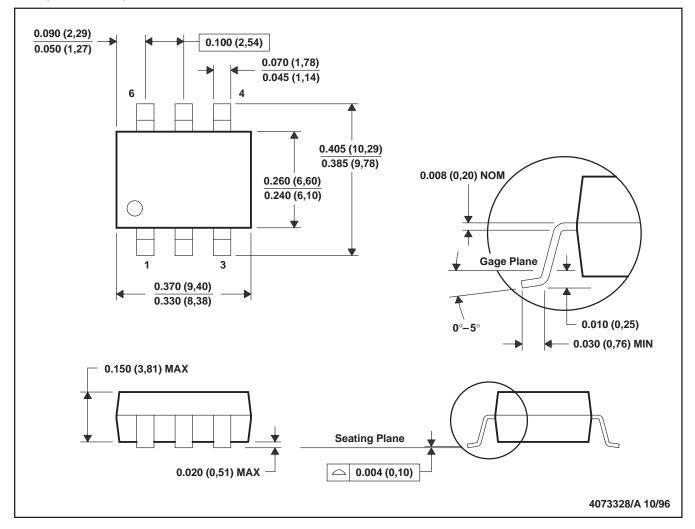
Figure 9. Plastic Dual-in-Line Package



MECHANICAL DATA

DCJ (R-PDSO-G6)

PLASTIC DUAL SMALL-OUTLINE OPTOCOUPLER



NOTES: A. All linear dimensions are in inches (millimeters)

B. This drawing is subject to change without notice.

C. Terminal 1 identified by index dot.

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